

## ●Features

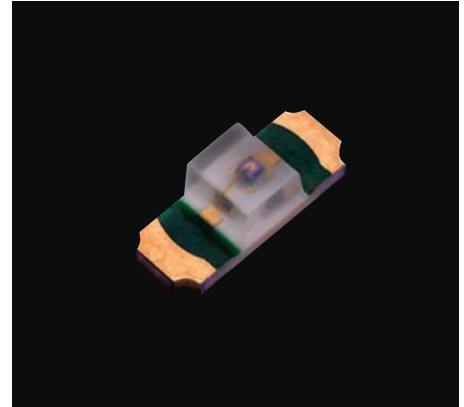
- Reverse-mount available type

## ●Size

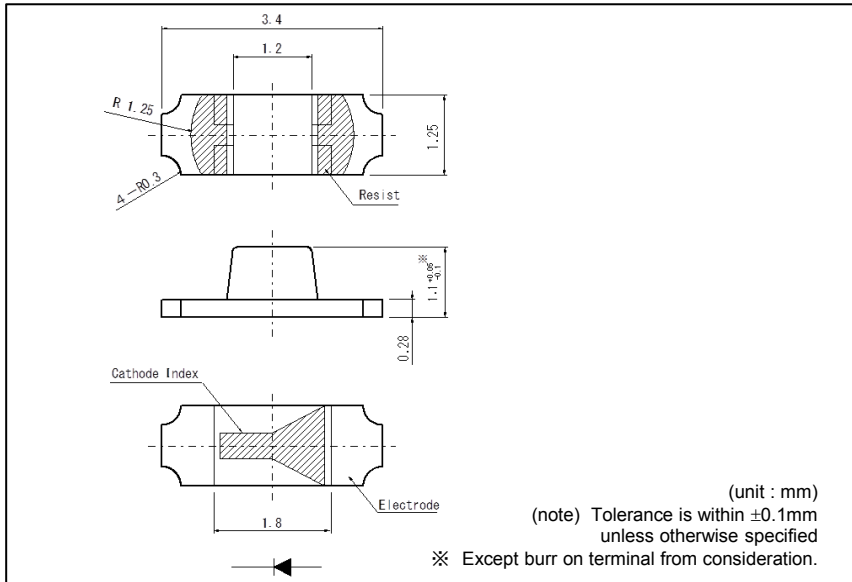
3412 (1305)  
3.4 × 1.25mm (t=1.1mm)



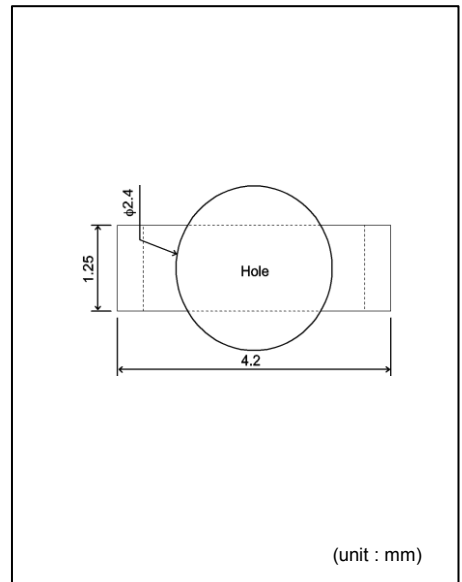
## ●Outline



## ●Dimensions



## ●Recommended Solder Pattern



## ●Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25°C)					Electrical and Optical Characteristics (Ta=25°C)											
			Power Dissipation P <sub>D</sub> (mW)	Forward Current I <sub>F</sub> (mA)	Peak Forward Current I <sub>FP</sub> (mA)	Reverse Voltage V <sub>R</sub> (V)	Operating Temp. Topr(°C)	Storage Temp. Tstg(°C)	Forward Voltage V <sub>F</sub> (V)	Reverse Current I <sub>R</sub> (μA)	Dominant Wavelength λ <sub>D</sub> (nm)			Luminous Intensity I <sub>v</sub> (mcd)					
SML-811VT(A)	AlGaInP	Red	62	25	100*2	5	-40 to +85	-40 to +100	1.95	10	100	5	625	630	636	10	11.2	22.4	10
SML-811UT(A)		Orange											615	620	625				
SML-811DT(A)		Yellow											602	605	608				
SML-811WT(A)		Yellowish Green											587	590	593				
SML-812MT		Blue											65	60*1	4				
SML812BCT	InGaN	White	80	20	100*2	5	-30 to +85	-40 to +85	3.3	5	10	5	464	470	476	5	22	56	5
SML813WBC8W	InGaN	White	33	10	50*2	5	-40 to +85	-40 to +100	2.9	5	10	5	(0.30, 0.30)			5	22	45	5

\*1:Duty1/5, 200Hz \*2:Duty1/10, 1kHz \*3:Reference

●Electrical Characteristics Curves

Fig.1 Forward Current - Forward Voltages

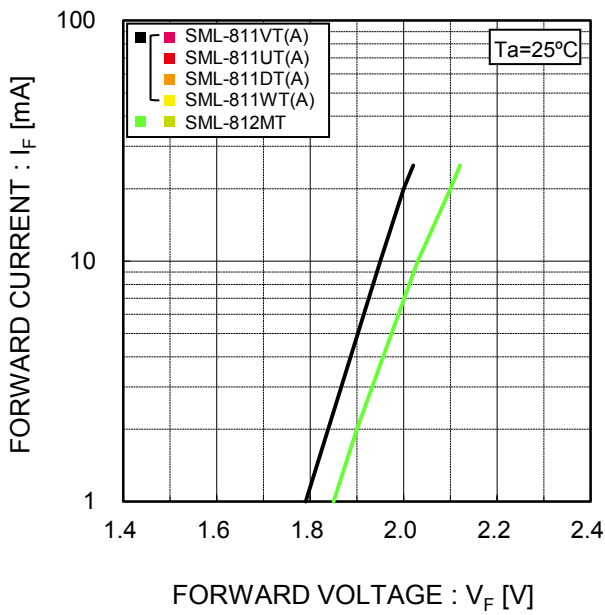


Fig.2 Luminous Intensity - Atmosphere Temperature

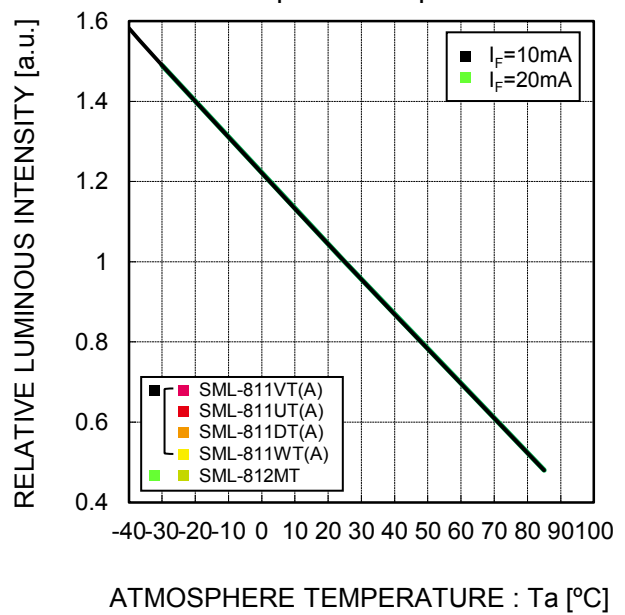


Fig.3 Luminous Intensity - Forward Current

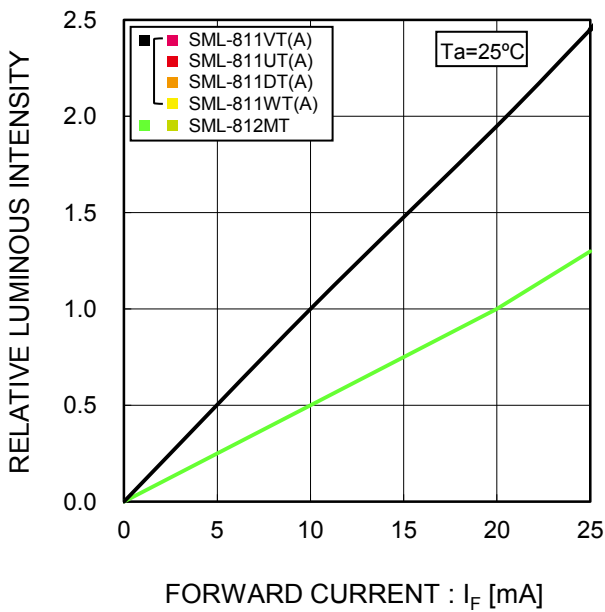
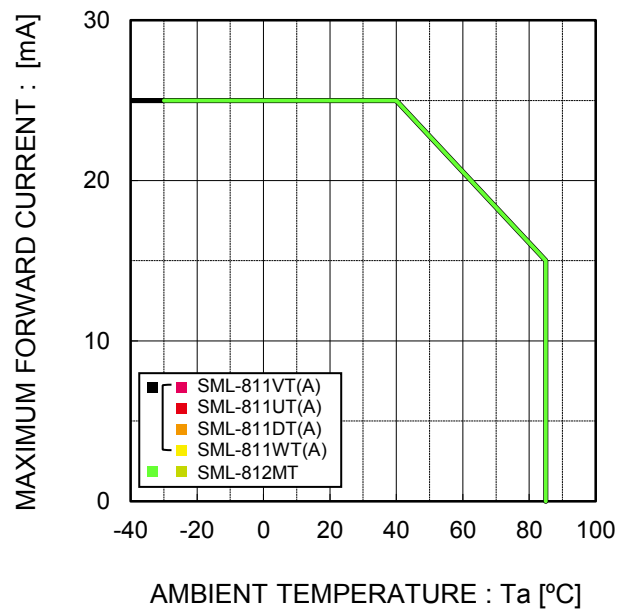


Fig.4 Derating



●Electrical Characteristics Curves

Fig.1 Forward Current - Forward Voltages

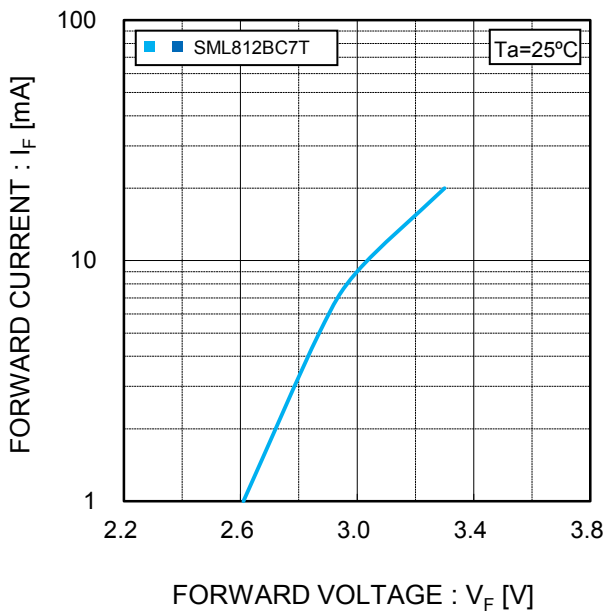


Fig.2 Luminous Intensity - Atmosphere Temperature

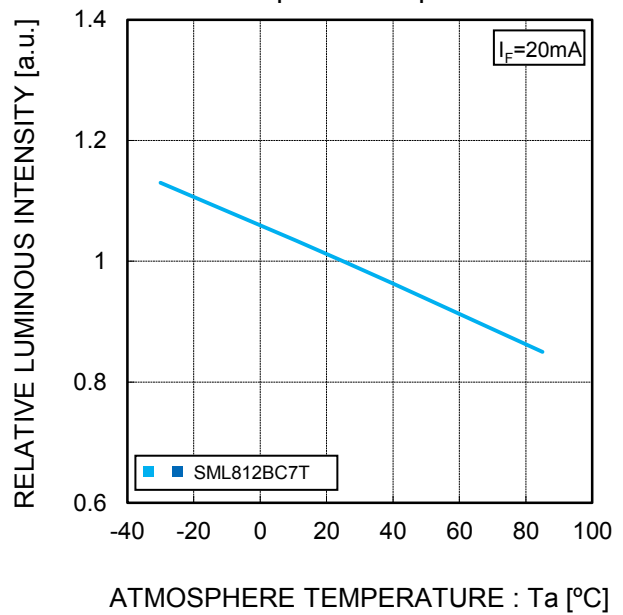


Fig.3 Luminous Intensity - Forward Current

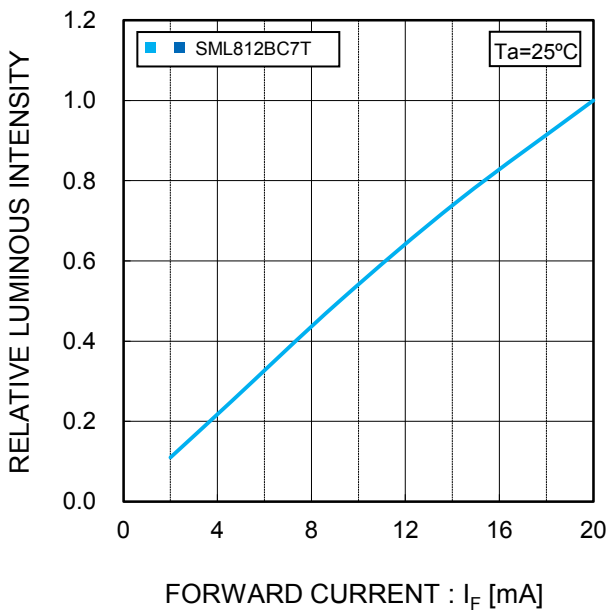
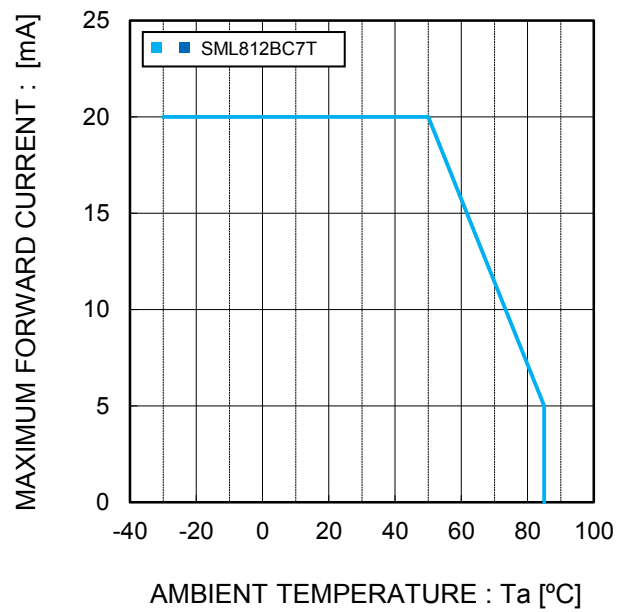


Fig.4 Derating



\*The value is based on the die destruction endurance; optical characteristics are NOT considered..

●Electrical Characteristics Curves

Fig.1 Forward Current - Forward Voltages

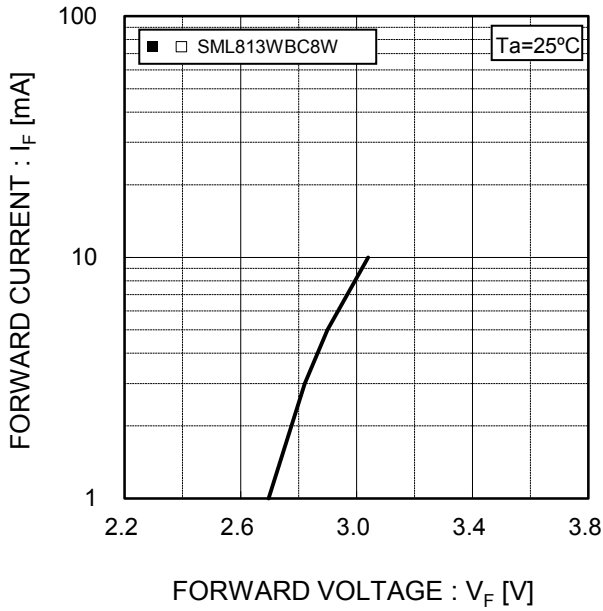


Fig.2 Luminous Intensity - Atmosphere Temperature

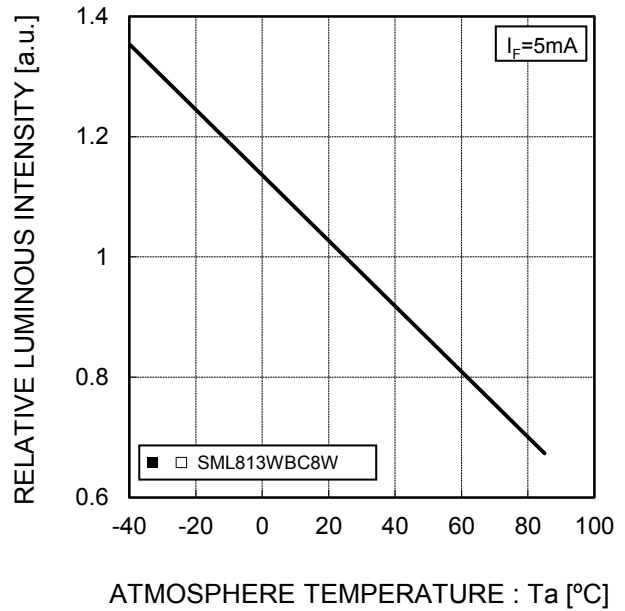


Fig.3 Luminous Intensity - Forward Current

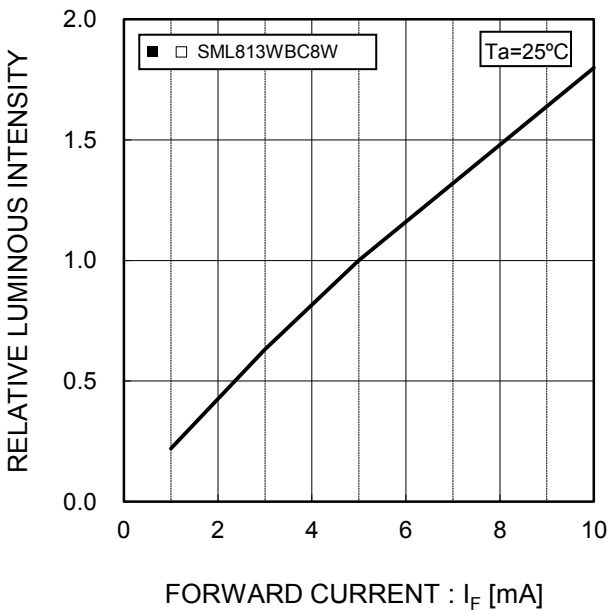
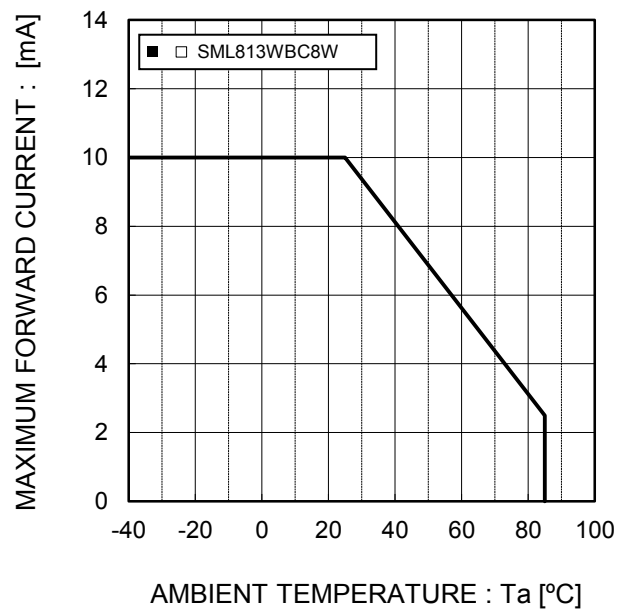
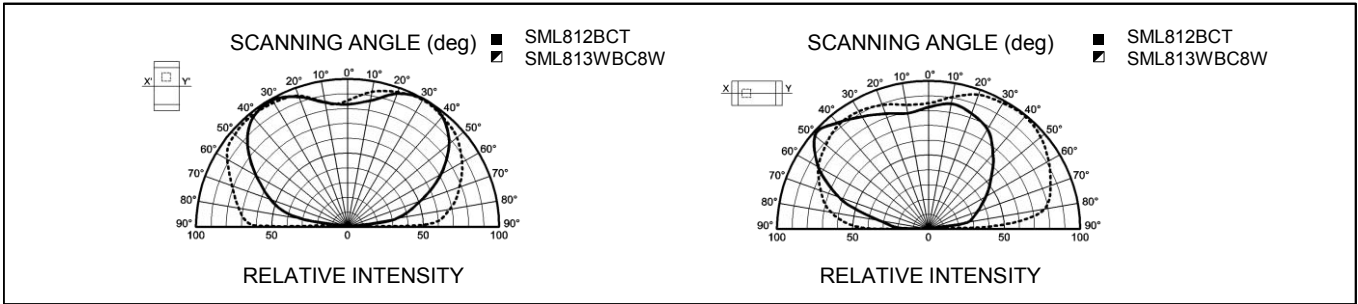
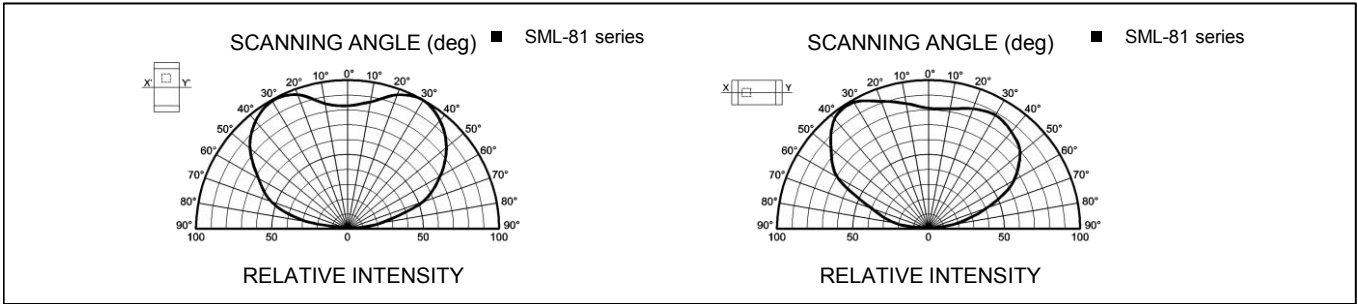


Fig.4 Derating



\*The value is based on the die destruction endurance; optical characteristics are NOT considered..

●Viewing Angle



●Rank Reference of Brightness

Red(V,U)

(Ta=25°C, If=10mA)

Rank	AG	AH	AJ	AK	AL	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX
Iv (mcd)	9.0 to 11.2	11.2 to 14	14 to 18	18 to 22.4	22.4 to 28	28 to 35.5	35.5 to 45	45 to 56	56 to 71	71 to 90	90 to 112	112 to 140	140 to 180	180 to 224	224 to 280	280 to 355
SML-811VT(A)*																
SML-811UT(A)*																

Orange(D)

(Ta=25°C, If=10mA)

Rank	AG	AH	AJ	AK	AL	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX
Iv (mcd)	9.0 to 11.2	11.2 to 14	14 to 18	18 to 22.4	22.4 to 28	28 to 35.5	35.5 to 45	45 to 56	56 to 71	71 to 90	90 to 112	112 to 140	140 to 180	180 to 224	224 to 280	280 to 355
SML-811DT(A)*																

Yellow(Y)

(Ta=25°C, If=10mA)

Rank	AG	AH	AJ	AK	AL	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX
Iv (mcd)	9.0 to 11.2	11.2 to 14	14 to 18	18 to 22.4	22.4 to 28	28 to 35.5	35.5 to 45	45 to 56	56 to 71	71 to 90	90 to 112	112 to 140	140 to 180	180 to 224	224 to 280	280 to 355
SML-811WT(A)*																

Green(M)

(Ta=25°C, If=20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X
Iv (mcd)	1.0 to 1.6	1.6 to 2.5	2.5 to 4.0	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-812MT※																

Blue(B)

(Ta=25°C, If=20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X
Iv (mcd)	0.9 to 1.4	1.4 to 2.2	2.2 to 3.6	3.6 to 5.6	5.6 to 9	9 to 14	14 to 22	22 to 36	36 to 56	56 to 90	90 to 140	140 to 220	220 to 360	360 to 560	560 to 900	900 to 1400
SML812BCT																

White(WB)

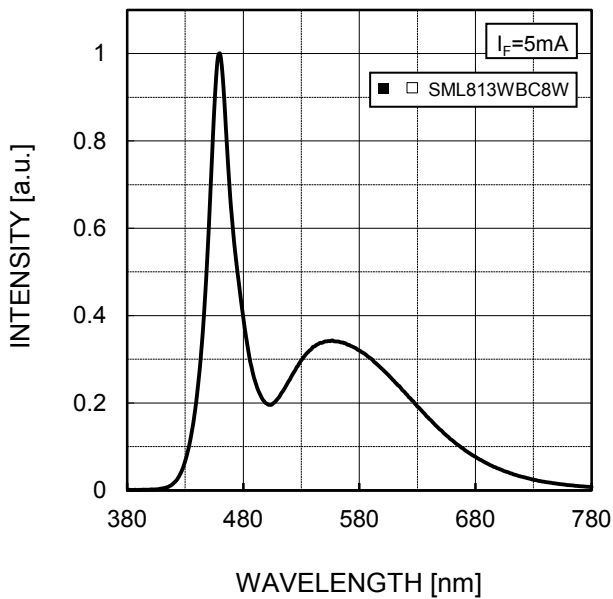
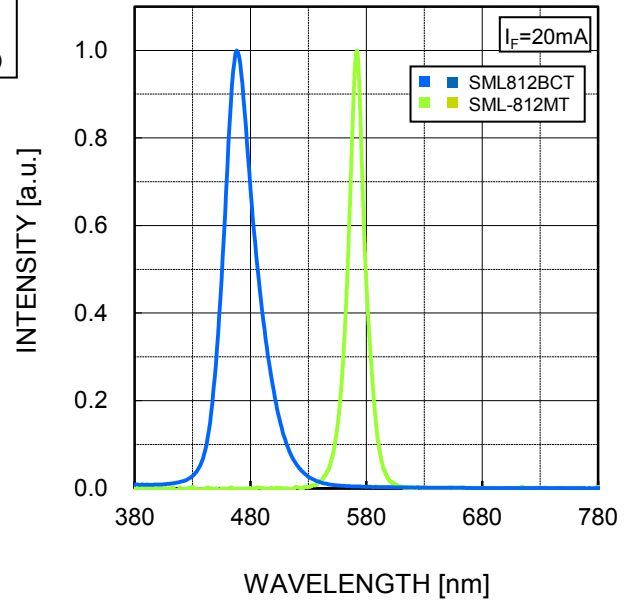
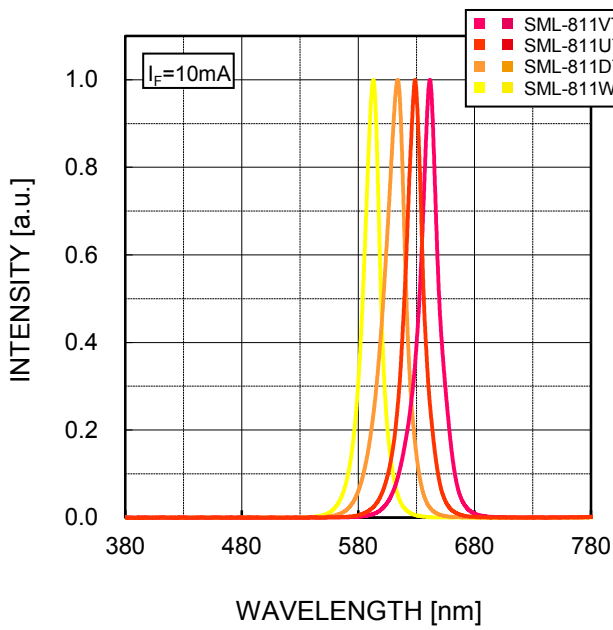
(Ta=25°C, If=5mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X
Iv (mcd)	0.9 to 1.4	1.4 to 2.2	2.2 to 3.6	3.6 to 5.6	5.6 to 9	9 to 14	14 to 22	22 to 36	36 to 56	56 to 90	90 to 140	140 to 220	220 to 360	360 to 560	560 to 900	900 to 1400
SML813WBC8W																

\*Please note that the brightness of some products may fall between ranks (half rank).

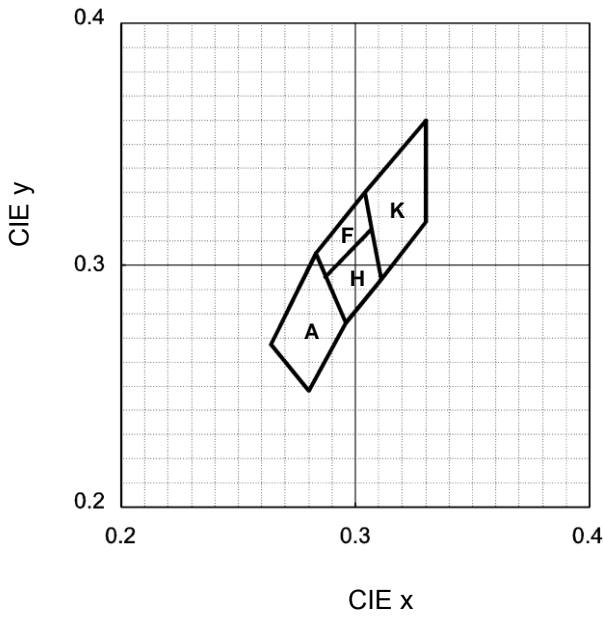
※Brightness on specification sheet include tolerance of within ±10%.

● Spectrum Data



\* Please take this data as a reference data for the samples are measured randomly.  
 \* The data is relativized for each color. It is NOT to show the spectrum peaks are equal.

●Chromaticity Diagram

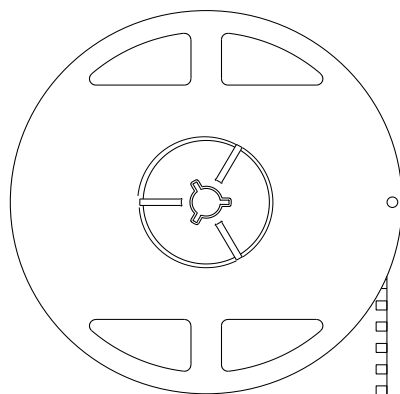
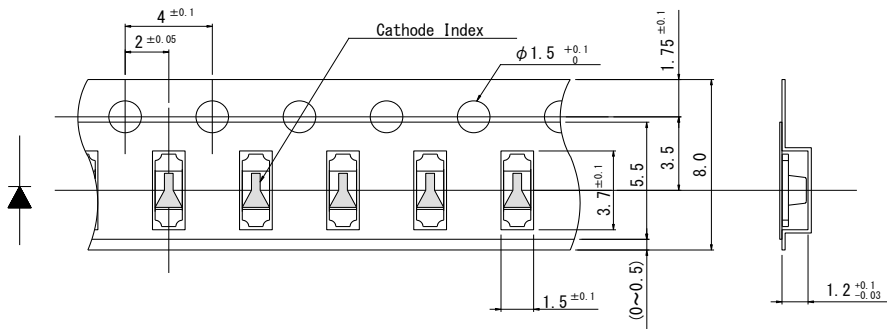


[Chromaticity Coordinates] (Ta=25°C, If=5mA)

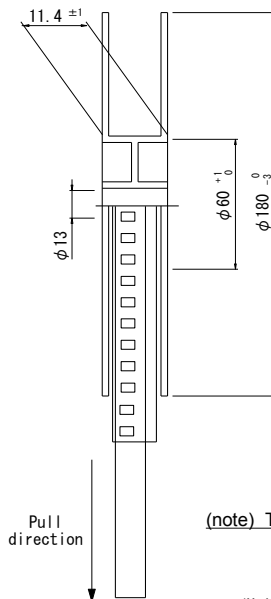
A		F		H		K	
x	y	x	y	x	y	x	y
0.280	0.248	0.283	0.305	0.287	0.295	0.304	0.330
0.296	0.276	0.304	0.330	0.307	0.315	0.330	0.360
0.283	0.305	0.307	0.315	0.311	0.294	0.330	0.318
0.264	0.267	0.287	0.295	0.296	0.276	0.311	0.294

Measurement tolerance : ±0.02

●Taping [T86 / 1(white)]



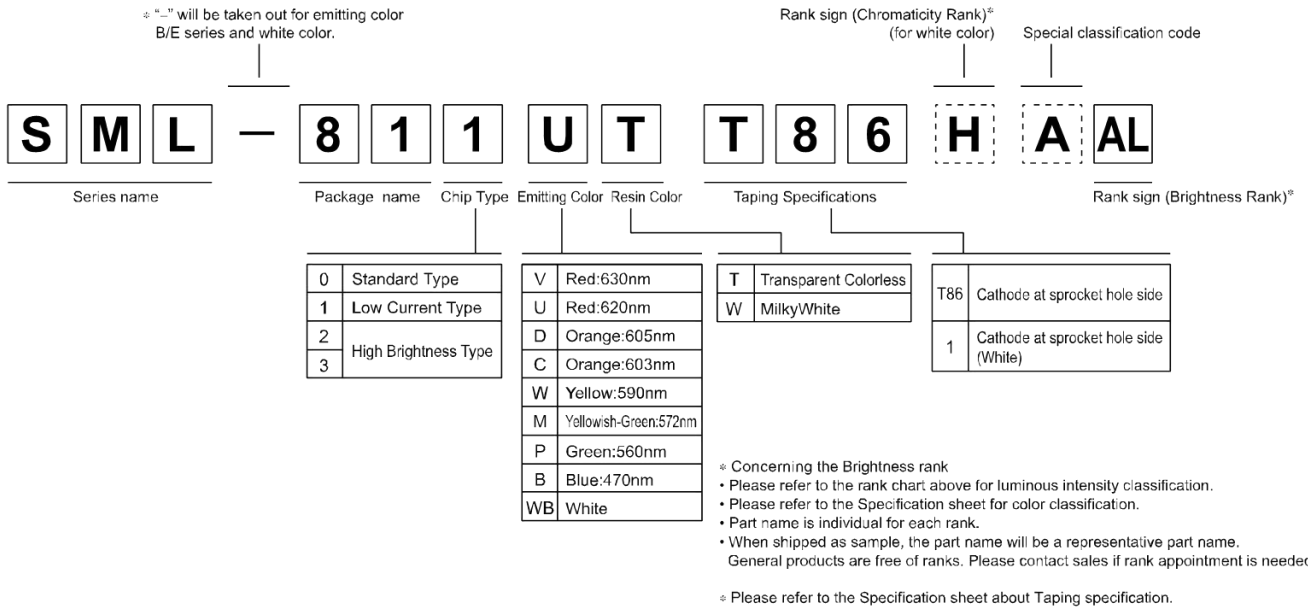
Packing quantity  
3000pcs/reel



(note) Tolerance is within ±0.2mm unless otherwise specified

(Unit : mm)  
( ) : Reference

●Part No. Construction



●Packing Specification

ROHM LED products are being shipped with desiccant (silica gel) concluded in moisture-proof bags.

Pasting the moisture sensitive label on the outer surface of the moisture-proof bags or enclosing the humidity indication card inside the bag is available upon request.

Please contact the nearest sales office or distributor if necessary.



## ●Attention Points In Handling

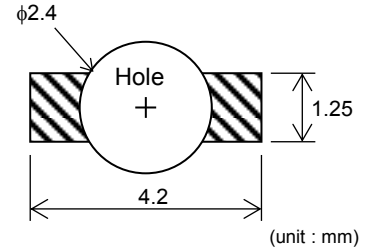
This product was developed as a surface mount LED especially suitable for soldering.  
Please take care of following points when using this device.

### 1.DESIGNING OF PCB

As for a recommendable solder pattern, Please refer to Fig-1.

The size and direction of the pad pattern depends on the condition of the PCB,  
Thorough design review is recommended before the final designing.

( This product of structured with rear/bottom electrode to be soldered.  
The formation of solder fillet is not guaranteed due to its electrode shape )



(unit : mm)  
(Fig-1)

### 2.SOLDERING (Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu)

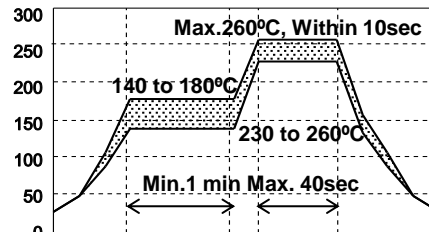
LED products do not contain reinforcement materials such as glass fillers.

Therefore, thermal stress by soldering greatly influence its reliability.

The temperature conditions for reflow soldering should therefore be set up according to the characteristic of this product. (See Fig-2)

Number of reflow process shall be max 2 times and these processes shall be performed in a row.

Cooling process to normal temperature shall be required between first and second soldering process.



(Fig-2)

### 3.WASHING

Please note the following points when washing is required after soldering.

#### 3-1) WASHING SOLVENT

Isopropyl alcohol or other alcohol solvent is recommendable.

#### 3-2) TEMPERATURE

Below 30°C, immersion time ; within 3 minutes.

#### 3-3) ULTRA SONIC WASHING

Below 15/1 litter of solvent tub.

#### 3-4) COOLING

Below 100°C within 3 minutes.

### 4.EROSION GAS

Utilization in erosion gas atmosphere may degenerate the plating surface which might cause deterioration of solder strength, optical characteristics, or functions.

Please take precautions against occurrence of gas from the surrounding parts on the occasion of custody, and also after mounted on circuit board.

## 5.STORAGE

At reflow soldering, the reliability of this product is often influenced by moisture absorption so we apply the packaging with moisture proof for better condition is use, please also note that

5-1) Not to be opened before using.

5-2) To be kept in our moisture proof packaging with some desiccant (SILICA GEL) after opening it.

To be baked in case the SILICA GEL indicator its color from either blue to clear or green to pink.

5-3) Please use within 168 hours after the package was opened. (Condition at 30°C, max.70%Rh.)

In case it is not used within 168 hours, please put it back into our packaging.

5-4) BAKING

Please bake under reel condition at 60°C, 12~24 hours (max.20%Rh) after un-sealing.

While baking is done, the reel and emboss tape may be easily deformed.

Please be careful not to give any stress.

## 6.LIFE TIME

This product will cause reduction of luminous intensity depending on the using conditions and environmental.

Please inquire our sales contact if long life time is required on your application.

## Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.  
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Products beyond the rating specified by ROHM.
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
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- 7) The Products specified in this document are not designed to be radiation tolerant.
- 8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
- 9) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
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### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

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Факс: +7 495 668-12-70 (доб.304)

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